SN65C3221, SN75C3221 3-V TO 5.5-V SINGLE-CHANNEL RS-232 COMPATIBLE LINE DRIVER/RECEIVER

SLLS351E - APRIL 2002 - REVISED OCTOBER 2004

- Operate With 3-V to 5.5-V V_{CC} Supply
- Operate Up To 1 Mbit/s
- **Low Standby Current . . . 1 μA Typ**
- External Capacitors . . . $4 \times 0.1 \mu F$
- Accepts 5-V Logic Input With 3.3-V Supply
- **RS-232 Bus-Pin ESD Protection Exceeds** ±15 kV Using Human-Body Model (HBM)
- **Auto-Powerdown Feature Automatically Disables Drivers for Power Savings**
- **Applications**
 - Battery-Powered, Hand-Held, and **Portable Equipment**
 - PDAs and Palmtop PCs
 - Notebooks, Sub-Notebooks, and Laptops
 - Digital Cameras
 - Mobile Phones and Wireless Devices

DB OR PW PACKAGE (TOP VIEW) $\overline{\mathsf{EN}}$ 16 FORCEOFF 15 V_{CC} C1+ [2 14∏ GND V+ **[**]3 13**∏** DOUT C1- Π 4 12 FORCEON C2+ [5 11 DIN C2-V− **∏**7 10 NVALID 9∏ ROUT RIN 8

description/ordering information

The SN65C3221 and SN75C3221 consist of one line driver, one line receiver, and a dual charge-pump circuit with ±15-kV ESD protection pin to pin (serial-port connection pins, including GND). These devices provide the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. These devices operate at data signaling rates up to 1 Mbit/s and a driver output slew rate of 24 V/μs to 150 V/μs.

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the devices do not sense a valid RS-232 signal on the receiver input, the driver output is disabled. If FORCEOFF is set low and EN is high, both the driver and receiver are shut off, and the supply current is reduced to 1 μ A. Disconnecting the serial port or turning off the peripheral drivers causes the auto-powerdown condition to occur. Auto-powerdown can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to the receiver input. The INVALID output notifies the user if an RS-232 signal is present at the receiver input. INVALID is high (valid data) if the receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30 μs. INVALID is low (invalid data) if the receiver input voltage is between –0.3 V and 0.3 V for more than 30 μs. Refer to Figure 5 for receiver input levels.

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP (DB)	Reel of 2000	SN75C3221DBR	CA3221
−0°C to 70°C	TOOOD (DIA))	Tube of 90	SN75C3221PW	040004
	TSSOP (PW)	Reel of 2000	SN75C3221PWR	CA3221
	SSOP (DB)	Reel of 2000	SN65C3221DBR	CB3221
-40°C to 85°C	TOOOD (DIA)	Tube of 90	SN65C3221PW	OD0004
	TSSOP (PW)	Reel of 2000	SN65C3221PWR	CB3221

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



Function Tables

EACH DRIVER

		INPUTS		OUTPUT	
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS
Х	Χ	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
Н	Н	Н	X	L	auto-powerdown disabled
L	L	Н	Yes	Н	Normal operation with
Н	L	Н	Yes	L	auto-powerdown enabled
L	L	Н	No	Z	Powered off by
Н	L	Н	No	Z	auto-powerdown feature

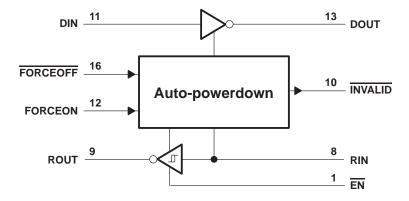
H = high level, L = low level, X = irrelevant, Z = high impedance

EACH RECEIVER

	INPUTS				
RIN	EN	VALID RIN RS-232 LEVEL	OUTPUT ROUT		
L	L	Х	Н		
Н	L	X	L		
X	Н	X	Z		
Open	L	No	Н		

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = disconnected input or connected driver off

logic diagram (positive logic)



SN65C3221, SN75C3221 3-V TO 5.5-V SINGLE-CHANNEL RS-232 COMPATIBLE LINE DRIVER/RECEIVER

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	–0.3 V to 6 V
Positive output supply voltage range, V+ (see Note 1)	–0.3 V to 7 V
Negative output supply voltage range, V– (see Note 1)	0.3 V to –7 V
Supply voltage difference, V+ – V– (see Note 1)	
Input voltage range, V _I : Driver (FORCEOFF, FORCEON, EN)	0.3 V to 6 V
Receiver	–25 V to 25 V
Output voltage range, VO: Driver	13.2 V to 13.2 V
Receiver (INVALID)	0.3 V to V _{CC} + 0.3 V
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DB package	82°C/W
PW package	108°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{sta}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to network GND.
 - 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 6)

				MIN	NOM	MAX	UNIT
	Overaltered		V _C C = 3.3 V	3	3.3	3.6	.,
	Supply voltage		V _{CC} = 5 V	4.5	5	5.5	V
.,	Driver and control high-level input voltage	DIN FORCES FORCES IN	V _{CC} = 3.3 V	2			.,
VIH		DIN, FORCEOFF, FORCEON, EN	V _{CC} = 5 V	2.4			V
V_{IL}	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON, EN				0.8	V
٧ _I	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
٧ _I	Receiver input voltage			-25		25	V
_			SN65C3221	-40		85	00
TA	Operating free-air temperature	SN75C3221	0		70	°C	

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAM	IETER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
II	Input leakage current	FORCEOFF, FORCEON, EN			±0.01	±1	μΑ
		Auto-powerdown disabled	No load, FORCEOFF and FORCEON at V _{CC}		0.3	1	mA
lcc	Supply current	Powered off	No load, FORCEOFF at GND		1	10	
	(T _A = 25°C)	Auto-powerdown enabled	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded		1	10	μΑ

[‡] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST	CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	DOUT at $R_L = 3 \text{ k}\Omega$ to GND,	DIN = GND	5	5.4		V
VOL	Low-level output voltage	DOUT at $R_L = 3 \text{ k}\Omega$ to GND,	DIN = V _{CC}	-5	-5.4		٧
lіН	High-level input current	VI = VCC			±0.01	±1	μΑ
I _{IL}	Low-level input current	V _I at GND			±0.01	±1	μΑ
		$V_{CC} = 3.6 \text{ V},$	V _O = 0 V		±35	±60	
los	Short-circuit output current‡	V _{CC} = 5.5 V,	VO = 0 V		±35	±90	mA
ro	Output resistance	V_{CC} , V+, and V- = 0 V,	$V_O = \pm 2 V$	300	10M		Ω
	Output lookage current	FORCEOFF = GND	$V_O = \pm 12 \text{ V}, V_{CC} = 3 \text{ V to } 3.6 \text{ V}$			±25	
loff	Output leakage current	FURGEOFF = GND	$V_O = \pm 10 \text{ V}, V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$			±25	μΑ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	-	TEST CONDITIONS			TYP	MAX	UNIT
			C _L = 1000 pF		250			
Maximum data rate (see Figure 1)		$R_L = 3 \text{ k}\Omega$	C _L = 250 pF,	$V_{CC} = 3 V \text{ to } 4.5 V$	1000			kbit/s
			C _L = 1000 pF,	F, $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$				
t _{sk(p)}	Pulse skew§	C _L = 150 pF to 2500 pF	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$	See Figure 2		100		ns
SR(tr)	Slew rate, transition region (see Figure 1)	V_{CC} = 3.3 V, R _L = 3 kΩ to 7 kΩ	C _L = 150 pF to 1000	pF	18		150	V/μs

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

ESD protection

TERMI	NAL	TECT COMPLETIONS	TVD	LINUT
NAME	NO.	TEST CONDITIONS T		UNIT
DOUT	13	НВМ	±15	kV



^{\$} Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

[§] Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 $V \pm 0.3 V$; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 $V \pm 0.5 V$.

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RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	$I_{OH} = -1 \text{ mA}$	V _{CC} – 0.6 V	V _{CC} – 0.1 V		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
\/	Decitive main a innext threehold walte as	V _{CC} = 3.3 V		1.6	2.4	V
V _{IT+}	Positive-going input threshold voltage	V _{CC} = 5 V		1.9	2.4	V
.,		V _{CC} = 3.3 V	0.6	1.1		V
V _{IT} –	Negative-going input threshold voltage	V _{CC} = 5 V	0.8	1.4		V
V _{hys}	Input hysteresis (V _{IT+} – V _{IT} _)			0.5		V
l _{off}	Output leakage current	FORCEOFF = 0 V		±0.05	±10	μΑ
rį	Input resistance	$V_1 = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	7	kΩ

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

	PARAMETER	TEST CONDITIONS	MIN TYP† MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	C _L = 150 pF, See Figure 3	150	ns
tPHL	Propagation delay time, high- to low-level output	C _L = 150 pF, See Figure 3	150	ns
t _{en}	Output enable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega, \text{See Figure 4}$	200	ns
tdis	Output disable time	C_L = 150 pF, R_L = 3 k Ω , See Figure 4	200	ns
tsk(p)	Pulse skew [‡]	See Figure 3	50	ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25^{\circ}\text{C}$.

NOTE 4: Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

ESD protection

TERMI	NAL	TEST COMPITIONS	TVD	LINUT
NAME NO.		TEST CONDITIONS	TYP	UNIT
RIN	8	HBM	±15	kV

[‡] Pulse skew is defined as |tpLH - tpHL| of each channel of the same device.

AUTO-POWERDOWN SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST (MIN	MAX	UNIT	
VT+(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	FORCEOFF = V _{CC}		2.7	V
VT-(valid)	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND,	FORCEOFF = V _{CC}	-2.7		V
V _T (invalid)	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND,	FORCEOFF = V _{CC}	-0.3	0.3	V
VOH	INVALID high-level output voltage	I _{OH} = -1 mA, FORCE FORCEOFF = V _{CC}	EON = GND,	V _{CC} -0.6		V
V _{OL}	INVALID low-level output voltage	I _{OL} = 1.6 mA, FORCE FORCEOFF = V _{CC}	EON = GND,		0.4	V

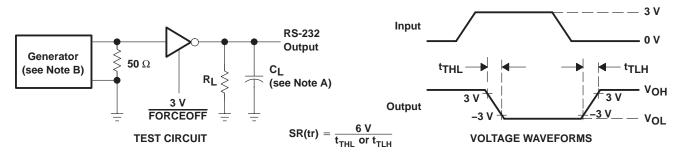
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	MIN 7	түр†	MAX	UNIT
tvalid	Propagation delay time, low- to high-level output		1		μs
tinvalid	Propagation delay time, high- to low-level output		30		μs
t _{en}	Supply enable time		100		μs

 $[\]dagger$ All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.



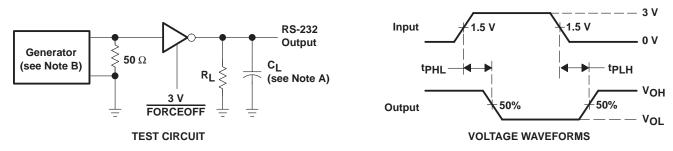
PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

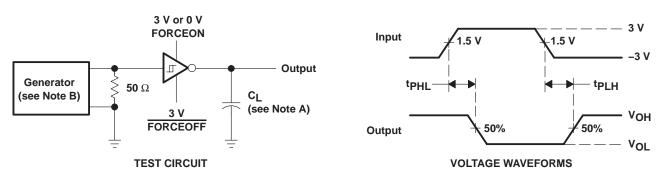
Figure 1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

Figure 2. Driver Pulse Skew

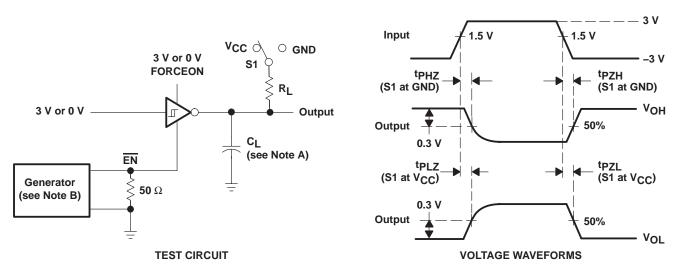


NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $Z_Q = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 3. Receiver Propagation Delay Times

PARAMETER MEASUREMENT INFORMATION

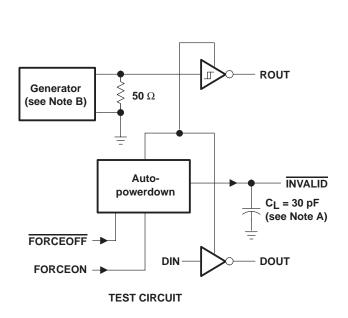


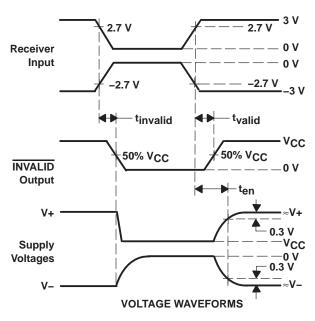
NOTES: A. C_L includes probe and jig capacitance.

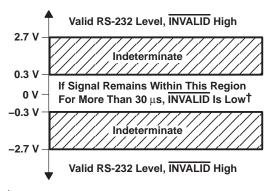
- B. The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.
- C. tpLZ and tpHZ are the same as tdis.
- D. tpzL and tpzH are the same as ten.

Figure 4. Receiver Enable and Disable Times

PARAMETER MEASUREMENT INFORMATION







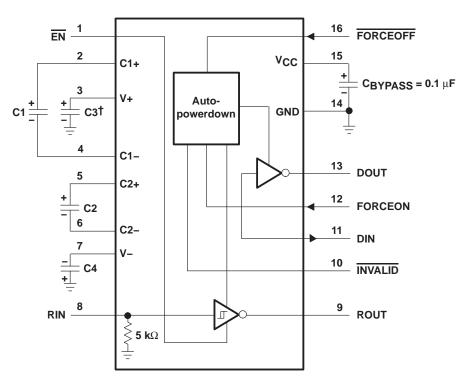
 $\mbox{\dagger}$ Auto-powerdown disables drivers and reduces supply current to 1 $\mu A.$

NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_\Gamma \le 10$ ns. $t_f \le 10$ ns.

Figure 5. INVALID Propagation Delay Times and Driver Enabling Time

APPLICATION INFORMATION



 $\ensuremath{^{\dagger}}\xspace \text{C3}$ can be connected to VCC or GND.

NOTE A: Resistor values shown are nominal.

V_{CC} vs CAPACITOR VALUES

VCC	C1	C2, C3, and C4				
$3.3~\text{V}\pm0.3~\text{V}$ 5 V \pm 0.5 V 3 V to 5.5 V	0.1 μF 0.047 μF 0.1 μF	0.1 μF 0.33 μF 0.47 μF				

Figure 6. Typical Operating Circuit and Capacitor Values





13-Oct-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN65C3221DB	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221DBE4	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221DBG4	ACTIVE	SSOP	DB	16	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221DBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221DBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN65C3221PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	CB3221	Samples
SN75C3221DBG4	OBSOLETE	SSOP	DB	16		TBD	Call TI	Call TI	0 to 70		
SN75C3221DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples
SN75C3221DBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples
SN75C3221DBRG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples
SN75C3221DW	PREVIEW	SOIC	DW	16	40	TBD	Call TI	Call TI	0 to 70		
SN75C3221PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples



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PACKAGE OPTION ADDENDUM

13-Oct-2013

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN75C3221PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples
SN75C3221PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples
SN75C3221PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples
SN75C3221PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples
SN75C3221PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	CA3221	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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PACKAGE OPTION ADDENDUM

13-Oct-2013

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OTHER QUALIFIED VERSIONS OF SN65C3221:

Automotive: SN65C3221-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65C3221DBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN65C3221PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN75C3221DBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN75C3221PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65C3221DBR	SSOP	DB	16	2000	367.0	367.0	38.0
SN65C3221PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN75C3221DBR	SSOP	DB	16	2000	367.0	367.0	38.0
SN75C3221PWR	TSSOP	PW	16	2000	367.0	367.0	35.0

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AA.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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